ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute									terials and M	fg Inforn	nation		
Supplier Inform	ation													
Company name*			Company unique ID			Unique ID Authority				Respons	Response Date*			
onsemi										2025-06	2025-06-02			
Contact Name			Title - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewa	rds	Produc	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requeste	1		m Number Mfr Item Name			Effective Date Version Manufactur  2025-06-02 PH4		Ianufacturing Site	,	Weight*	UOM	Unit Type		
			TCX 8 BIT 5V/3V T	B BIT 5V/3V TRANSLATOR				H4	89.202		mg	Each		
Ianufacturing	Proccess Information													
Terminal l	nal Plating / Grid Array Material		Terminal Base Alloy		SL Rating	Peak Process Body Temperatur		re Max Time at Peak Tempera		rature Number of Reflow Cycles				
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		(no CU Alloy	CU Alloy 1			260		C 30		secon	seconds 3			
comments														
vel 1 - maximum ti	ime at peak temperature du	ring soldering i	is 10-30 seconds											
	on regarding material comp													

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this for											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.736	mg	Supplier	Silicon (Si)	7440-21-3		0.736	mg
Die Attach	0.08	mg		Bismaleimide Resin	proprietary data		0.0132	mg
			Supplier	Other Additive Agents	Proprietary Data		0.0028	mg
			Supplier	Silver (Ag)	7440-22-4		0.064	mg
Lead Frame	38.024	mg	Supplier	Zinc (Zn)	7440-66-6		0.0456	mg
			Supplier	Iron (Fe)	7439-89-6		0.8936	mg
			Supplier	Copper (Cu)	7440-50-8		37.0734	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0114	mg
Mold Compound-Black	49.5	mg		Epoxy resin	proprietary data		4.7025	mg
			Supplier	Phenol Resin	Proprietary Data		2.475	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2475	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		42.075	mg
Plating	0.266	mg	Supplier	Palladium (Pd)	7440-05-3		0.0091	mg
			В	Nickel (Ni)	7440-02-0		0.2539	mg
			Supplier	Gold (Au)	7440-57-5		0.003	mg
Wire Bond - Au	0.596	mg	Supplier	Gold (Au)	7440-57-5		0.596	mg